



Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
01	<u> </u>	1.7Ω @ V _{GS} = 10V	500mA
Q1	Q1 60V	3Ω @ V _{GS} = 4.5V	400mA
	001/	4Ω @ V _{GS} = -10V	-360mA
Q2	Q2 -60V	6Ω @ V _{GS} = -4.5V	-310mA

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch



Top View

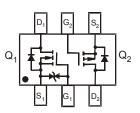
COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.027 grams (approximate)



Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMG1029SV-7	Standard	SOT563	3000/Tape & Reel
DMG1029SVQ-7	Automotive	SOT563	3000/Tape & Reel

Bottom View

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

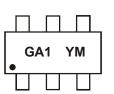
 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

 Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.

Marking Information



GA1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

Notes:

Date eeae hey												
Year	200	Э	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Y	Z	2	A		В		С
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	60	V	
Gate-Source Voltage		V _{GSS}	±20	V	
	Steady State	T _A = +25°C T _A = +70°C	ID	500 400	mA
Continuous Drain Current (Note 7) $V_{GS} = 10V$ t<10s $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$			Ι _D	620 480	mA
Pulsed Drain Current (Note 7)	I _{DM}	1000	mA		

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage	V _{DSS}	-60	V		
Gate-Source Voltage	V _{GSS}	±20	V		
	Steady State	T _A = +25°C T _A = +70°C	I _D	-360 -280	mA
Continuous Drain Current (Note 7) $V_{GS} = -10V$ t<10s $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$			ID	-410 -320	mA
Pulsed Drain Current (Note 7)	I _{DM}	-650	mA		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Total Dower Dissinction (Note 6)	T _A = +25°C	Р	0.45	W	
Total Power Dissipation (Note 6)	T _A = +70°C	PD	0.28		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	281	°C/W	
	t<10s	$R_{ extsf{ heta}JA}$	210		
Total Bower Dissinction (Note 7)	T _A = +25°C	D	1	W	
Total Power Dissipation (Note 7)	T _A = +70°C	PD	0.62	vv	
Thermal Registered, Junction to Ambient (Note 7)	Steady state	P	129	°C/W	
Thermal Resistance, Junction to Ambient (Note 7)	t<10s	$R_{ extsf{ heta}JA}$	97	0/00	
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



Electrical Characteristics N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current $@T_C = +25^{\circ}C$			_	10	nA	V _{DS} =50V, V _{GS} = 0V
Gate-Source Leakage	IGSS		_	±50	nA	$V_{GS} = \pm 5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)			•	•		
Gate Threshold Voltage		1.0	_	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Statia Drain Source On Desistance		_	1.3	1.7	0	V _{GS} = 10V, I _D = 500mA
Static Drain-Source On-Resistance	R _{DS(ON)}		1.5	3	Ω	V _{GS} = 4.5V, I _D = 200mA
Forward Transfer Admittance		80	_	_	mS	V _{DS} = 10V, I _D = 200mA
Diode Forward Voltage				1.4	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 9)			•	•		
Input Capacitance	C _{iss}	_	30	_	pF	
Output Capacitance	Coss	_	4.2	—	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	2.9	—	pF	
Total Gate Charge	Qg		0.3	_	nC	
Gate-Source Charge	Q _{gs}		0.2	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge			0.08	—	nC	– I _D = 250mA
Turn-On Delay Time	t _{D(on)}	-	3.9	—	ns	
Turn-On Rise Time		-	3.4	—	ns	V _{DD} = 30V, V _{GS} = 10V,
Turn-Off Delay Time	t _{D(off)}	_	15.7	_	ns	R _G = 25Ω, I _D = 200mA
Turn-Off Fall Time	t _f	_	9.9	—	ns	

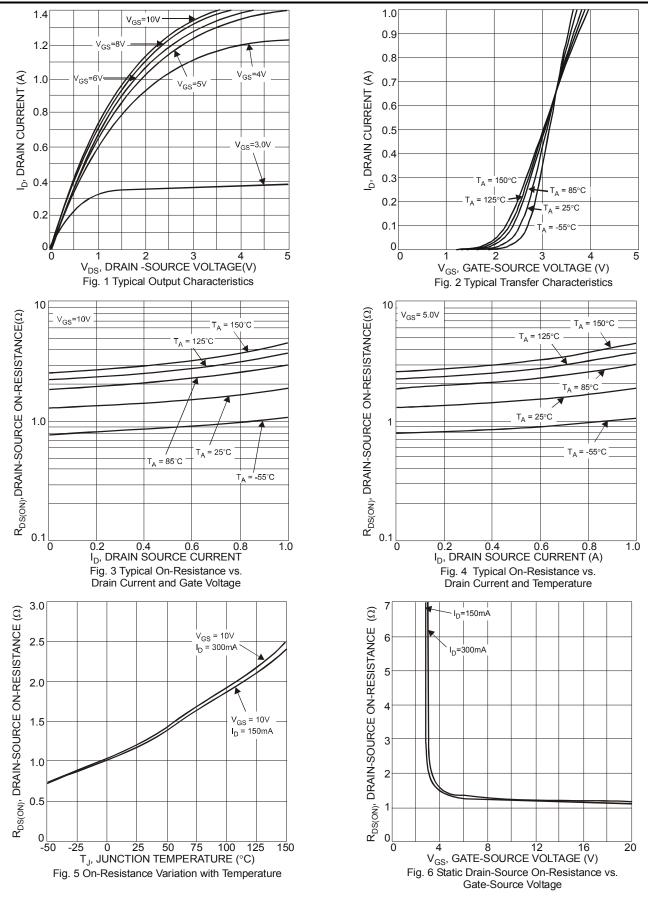
Electrical Characteristics P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_	—	V	$V_{GS} = 0V, I_D = -250 \mu A$
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	—	_	-25	nA	V _{DS} = -50V, V _{GS} = 0V
Gate-Source Leakage		—	_	±100	nA	V_{GS} = ±5V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	-1	_	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	R _{DS (ON)}	—	2.7	4	Ω	V _{GS} = -10V, I _D = -500mA
Static Drain-Source On-Resistance		_	3.2	6	12	V _{GS} = -4.5V, I _D = -200mA
Forward Transfer Admittance	Y _{fs}	50		—	mS	V _{DS} = -25V, I _D = -100mA
Diode Forward Voltage	V _{SD}	_	_	-1.4	V	V _{GS} = 0V, I _S = -115mA
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	25	—	pF	
Output Capacitance	Coss	—	4.7	—	pF	V _{DS} = -25V, V _{GS} = 0V, f = 1 0MHz
Reverse Transfer Capacitance	C _{rss}	—	2.7	—	pF	
Total Gate Charge	Qg	_	0.28	—	nC	
Gate-Source Charge	Q _{gs}	_	0.14	—	nC	−V _{GS} = -4.5V, V _{DS} = -10V, −I _D = -500mA
Gate-Drain Charge	Q _{gd}	_	0.08	—	nC	
Turn-On Delay Time		—	5.5	—	ns	
Turn-On Rise Time		—	7.9	—	ns	V _{DD} = -30V, V _{GS} = -10V,
Turn-Off Delay Time		—	10.6	—	ns	R _G = 50Ω, I _D = -270mA
Turn-Off Fall Time	t _f	—	11.6	—	ns	

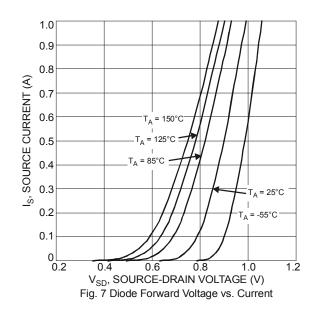
Notes:8. Short duration pulse test used to minimize self-heating effect.9. Guaranteed by design. Not subject to product testing.

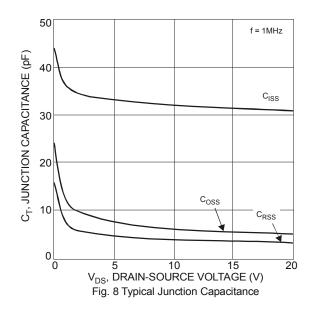


N-CHANNEL – Q1



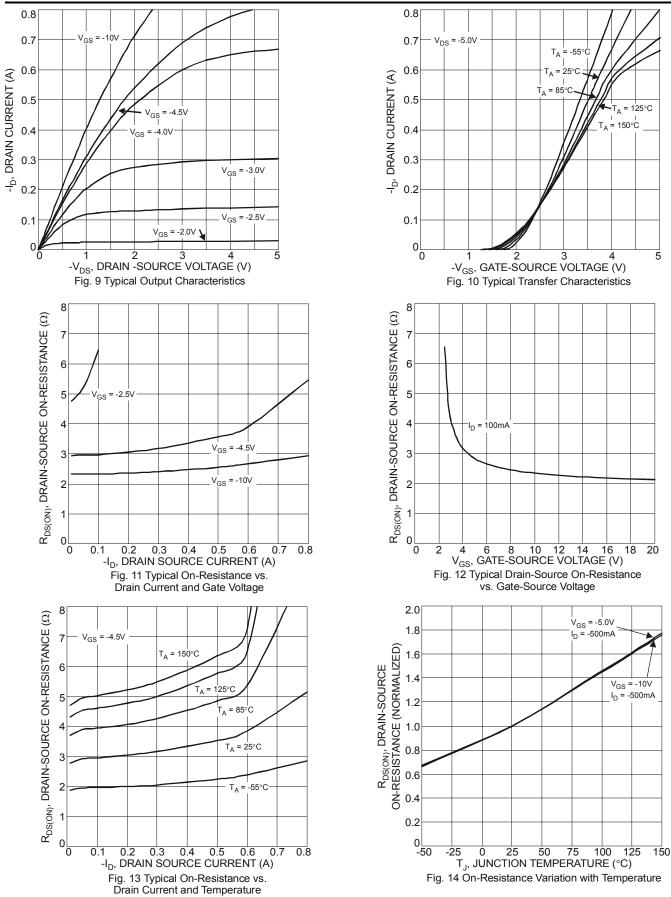






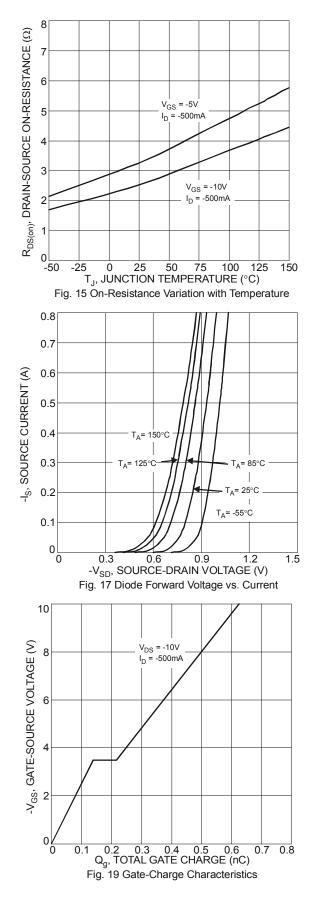


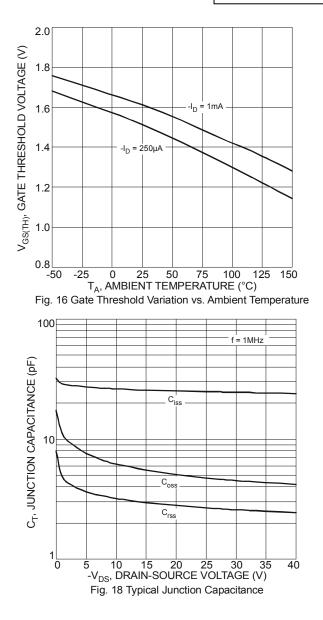








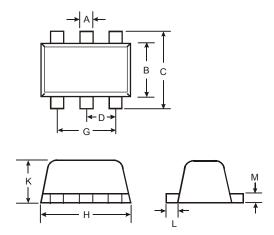






Package Outline Dimensions

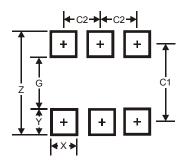
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SO	T563	
Dim	Min	Max	Тур
Α	0.15	0.30	0.20
В	1.10	1.25	1.20
С	1.55	1.70	1.60
D	-		
G	0.90	1.10	1.00
Н	1.50	1.70	1.60
Κ	0.55	0.60	0.60
L	0.10	0.30	0.20
М	0.10	0.18	0.11
All	Dimens	ions in	mm

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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